

Supporting Information for:

A silica co-electrodeposition route to highly active Ni-based film electrode

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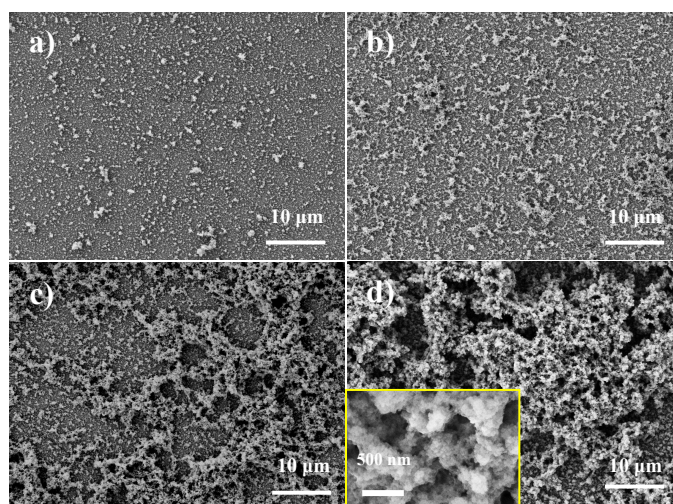


Fig. S1 Morphology of the SiO₂ films electrodeposited at -1.1 V vs. Ag/AgCl for 600 s (a), 1200 s (b), 1800 s (c) and 2400 s (d). The deposition precursor contains 45 mL of 0.2 M Na₂SO₄ / 0.2 M H₃BO₃, 5 mL ethanol and 0.25 mL TMOS. Inset shows the high magnification image.

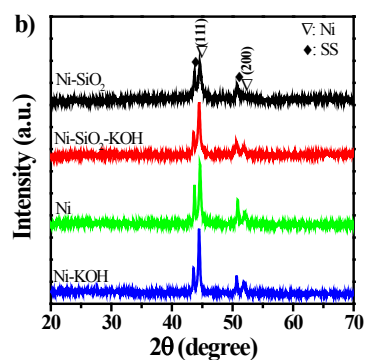


Fig. S2. XRD patterns of Ni and Ni-SiO₂ films before and after 50 repeated CV scans in 1.0 M KOH.

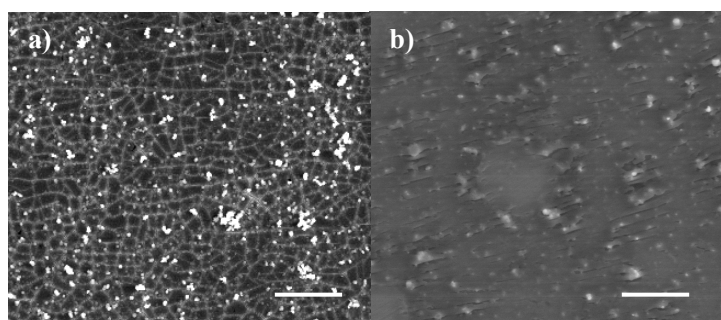


Fig. S3 SEM (a) and environment-SEM (b) images of the Ni-SiO₂ films. The scale bars correspond to 25 μm.

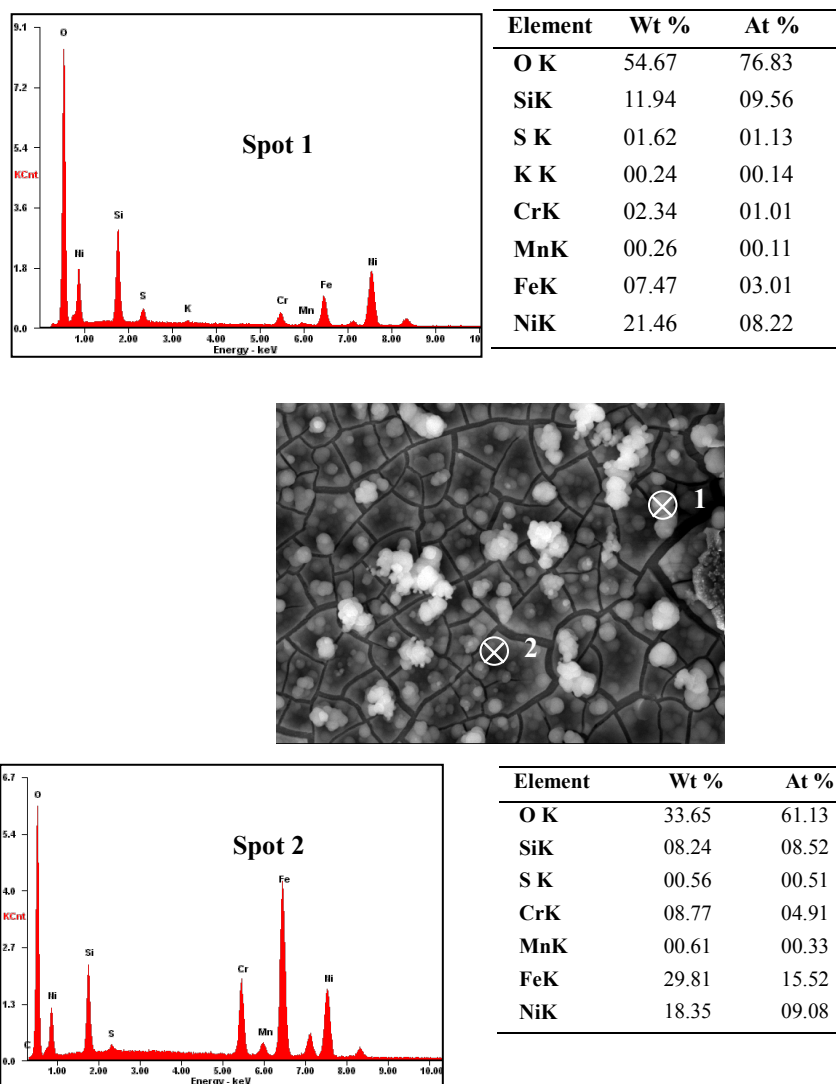
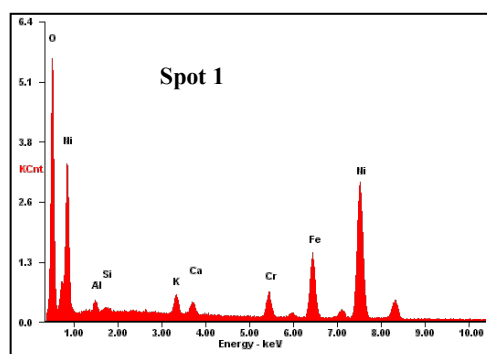
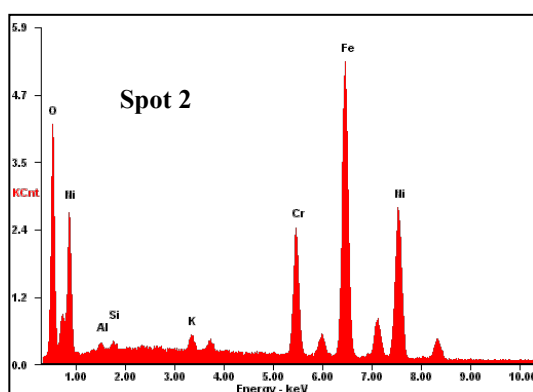
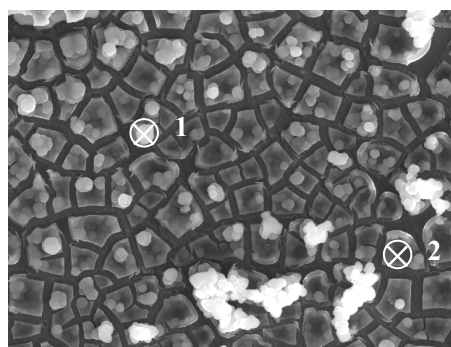


Fig. S4 A scanning electron microscopy graph of a SS electrode coated with Ni-SiO₂ film, and the energy dispersive spectra taken from two typical positions of the film. The elements of Cr, Fe and Mn are from the SS substrate.



Element	Wt %	At %
O K	40.72	70.04
AlK	01.83	01.87
SiK	00.51	00.50
K K	01.75	01.23
CrK	03.53	01.87
FeK	11.78	05.80
NiK	39.88	18.69



Element	Wt %	At %
O K	23.10	50.73
AlK	00.95	01.24
SiK	00.67	00.84
K K	00.88	00.79
CrK	10.29	06.95
FeK	35.73	22.48
NiK	28.38	16.98

Fig. S5 A scanning electron microscopy graph of a SS electrode coated with Ni-SiO₂-KOH film, and the energy dispersive spectra taken from two typical positions of the film. The elements of Cr, Fe and Mn are from the SS substrate.

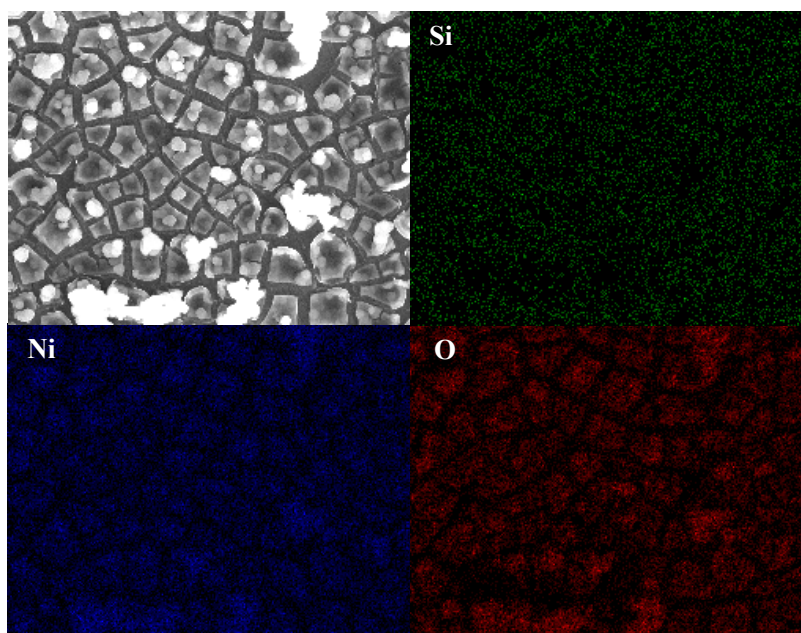


Fig. S6 A scanning electron micrograph of a SS electrode coated with Ni-SiO₂ film after underwent 50 repeated CV scan in 1.0 M KOH at scan rate of 20 mV s⁻¹ and the corresponding energy dispersive X-ray maps of the same sample showing the dispersion of Si, O, Ni on the SS surface.

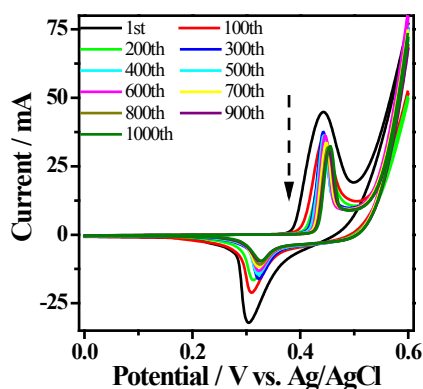


Fig. S7 Consecutive CV curves between 0 and 0.6 V for po-Ni film conducted in 1.0 M KOH at scan rate of 100 mV s⁻¹. The dotted arrow indicates the change direction of the anodic current density with the increasing scan number.

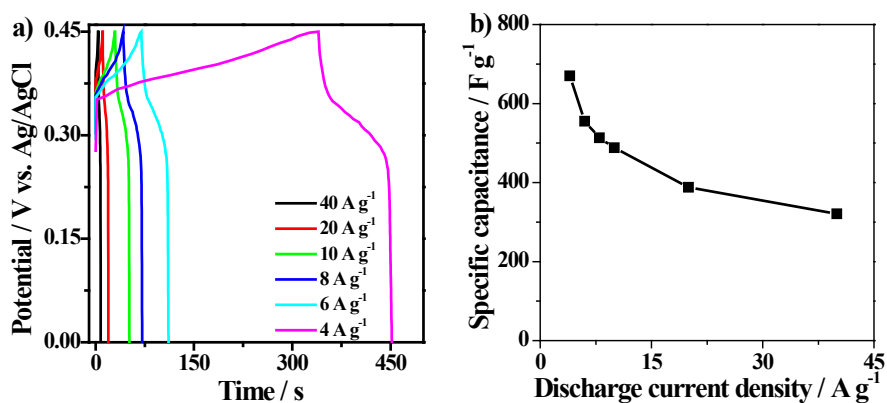


Fig. S8 (a) Galvanostatic charge-discharge curves at 4 - 40 A g⁻¹, (b) specific capacitance calculated from discharge curves of the po-Ni films in 1.0 M KOH.

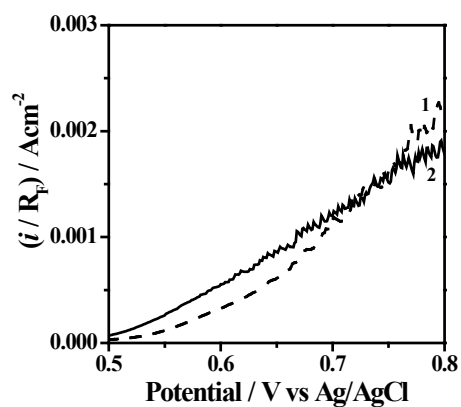


Fig. S9 The roughness factor-normalized current polarization curves toward OER for Ni (1) and po-Ni (2) film electrodes in 1.0 M KOH.

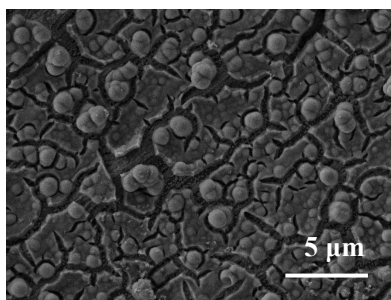


Fig. S10 SEM image of po-Ni film electrode after underwent 5 days electrolysis in 1.0 M KOH at 100 mA cm⁻².

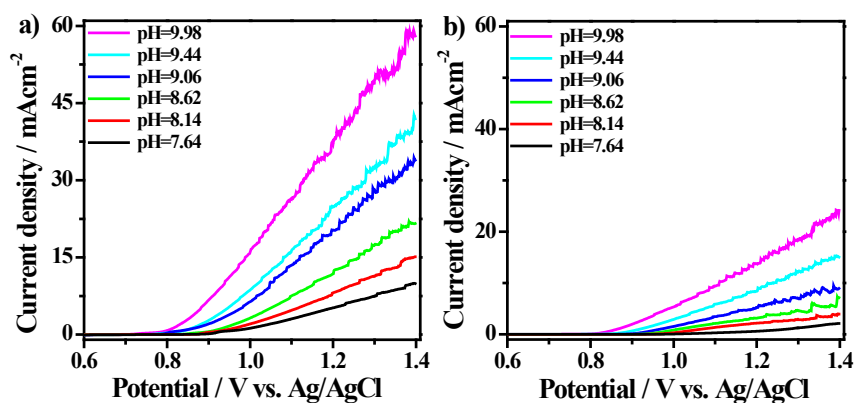


Fig. S11 Steady-state polarization curves of po-Ni (a) and Ni (b) films recorded in 1.0 M H₃BO₃ with a series of pH from 7.64 to 9.98.